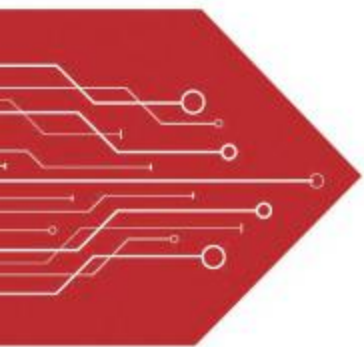


MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



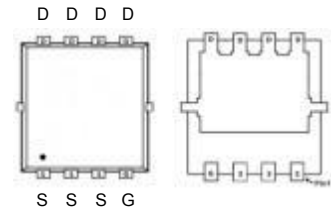
PLED

Product data sheet

Description

The MSK30P02DF is the high cell density trenched P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The MSK30P02DF meet the RoHS and Green Product requirement with full function reliability approved.

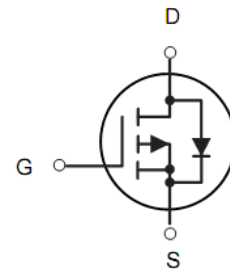


DFN3X3-8L

Product Summary

BVDSS	RDSON	ID
-20V	10mΩ	-30A

- ★ Super Low Gate Charge
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology



P-Channel MOSFET

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	-20	V
V _{GS}	Gate-Source Voltage	±12	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ -4.5V ¹	-30	A
I _D @T _C =70°C	Continuous Drain Current, V _{GS} @ -4.5V ¹	-18	A
I _{DM}	Pulsed Drain Current ²	-68	A
P _D @T _C =25°C	Total Power Dissipation ³	18	W
P _D @T _C =70°C	Total Power Dissipation ³	12	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	75	°C/W
R _{θJA}	Thermal Resistance Junction-Ambient ¹ (t ≤10s)	40	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	4.2	°C/W

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-20	---	---	V
ΔBV _{DSS} /ΔT _J	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =-1mA	---	-0.012	---	V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =-4.5V , I _D =-10A	---	10	15	mΩ
		V _{GS} =-2.5V , I _D =-8A	---	13	18	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =-250uA	-0.4	-0.7	-1.0	V
ΔV _{GS(th)}	V _{GS(th)} Temperature Coefficient		---	2.94	---	mV/°C
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-15V , V _{GS} =0V , T _J =25°C	---	---	1	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} = ±12 V , V _{DS} =0V	---	---	±100	nA
g _{fs}	Forward Transconductance	V _{DS} =-5V , I _D =-10A	---	43	---	S
Q _g	Total Gate Charge (-4.5V)	V _{DS} =-10V , V _{GS} =-4.5V , I _D =-10A	---	35	---	nC
Q _{gs}	Gate-Source Charge		---	5.0	---	
Q _{gd}	Gate-Drain Charge		---	10	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =-10V , V _{GS} =-4.5V , R _G =3.3Ω , I _D =-10A	---	12.0	---	ns
T _r	Rise Time		---	40.0	---	
T _{d(off)}	Turn-Off Delay Time		---	30	---	
T _f	Fall Time		---	10	---	
C _{iss}	Input Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz	---	2800	---	pF
C _{oss}	Output Capacitance		---	690	---	
C _{rss}	Reverse Transfer Capacitance		---	590	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current ^{1,4}	V _G =V _D =0V , Force Current	---	---	-30.0	A
I _{SM}	Pulsed Source Current ^{2,4}		---	---	---	A
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25°C	---	---	-1.2	V
t _{rr}	Reverse Recovery Time	I _F =-10A , dI/dt=100A/μs ,	---	27	---	nS
Q _{rr}	Reverse Recovery Charge	T _J =25°C	---	17.8	---	nC

Note :

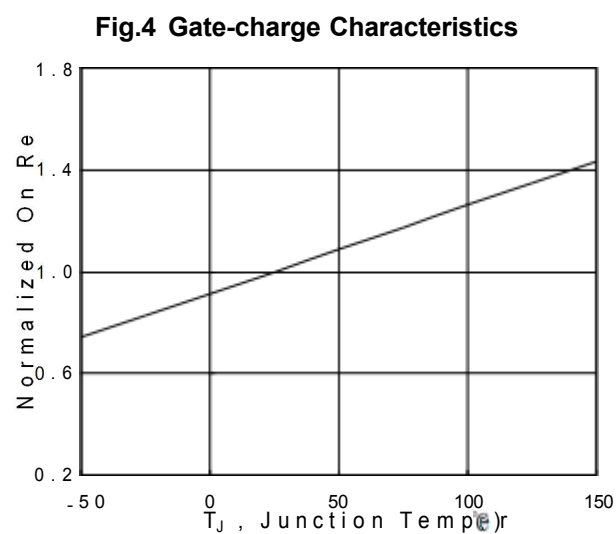
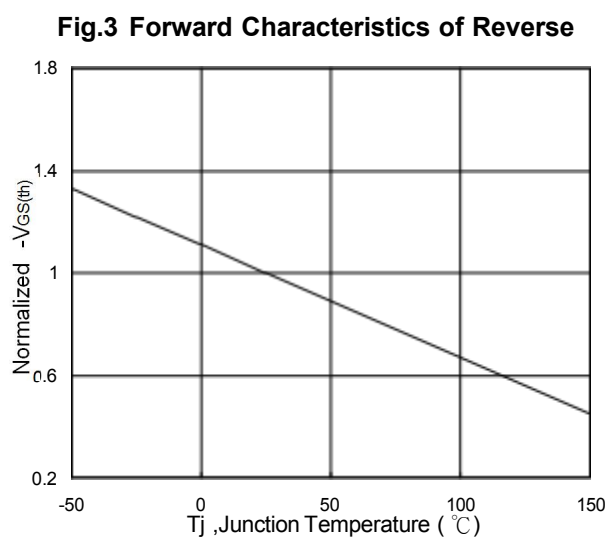
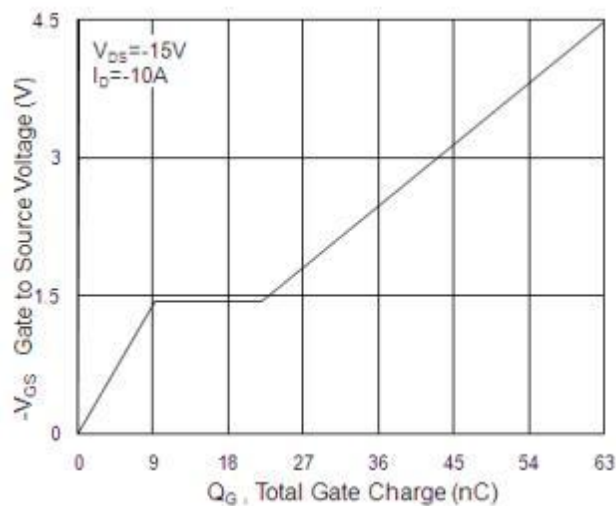
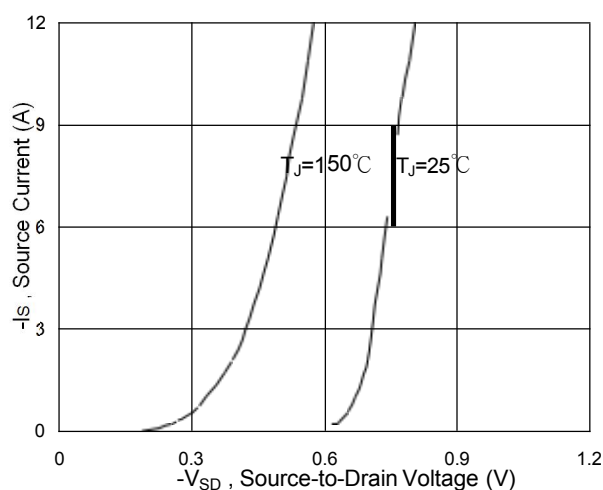
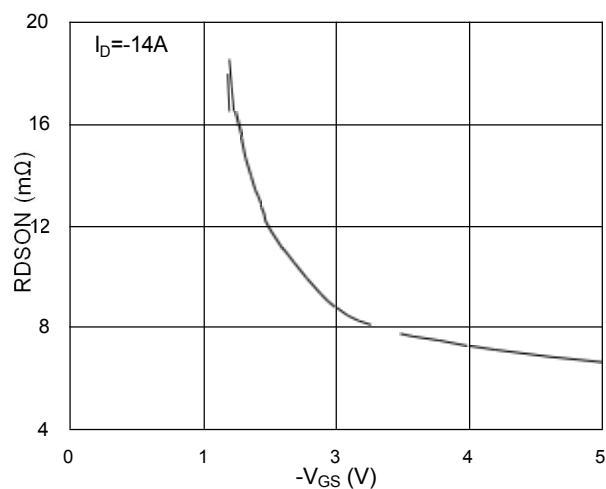
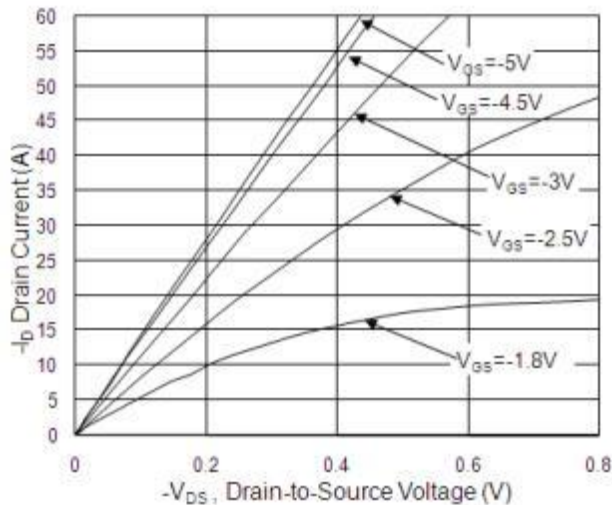
1.The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.

2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%

3.The power dissipation is limited by 150°C junction temperature

4.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics



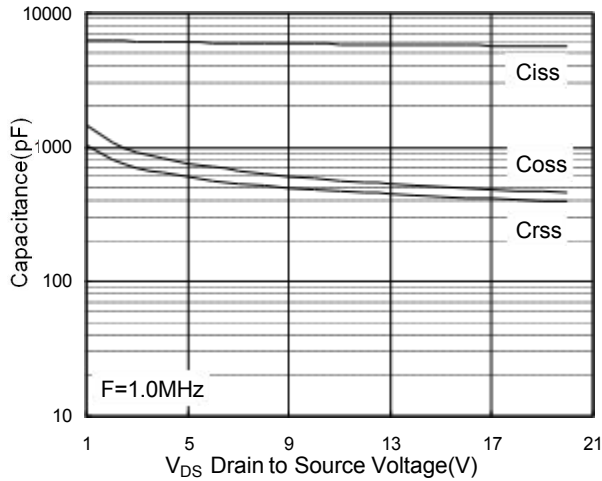


Fig.7 Capacitance

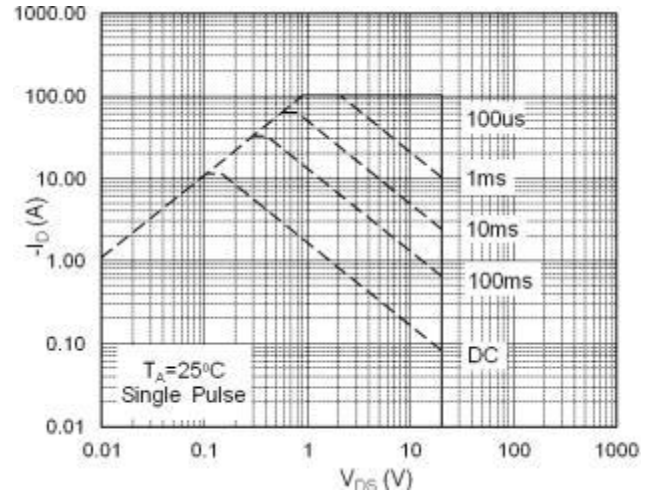


Fig.8 Safe Operating Area

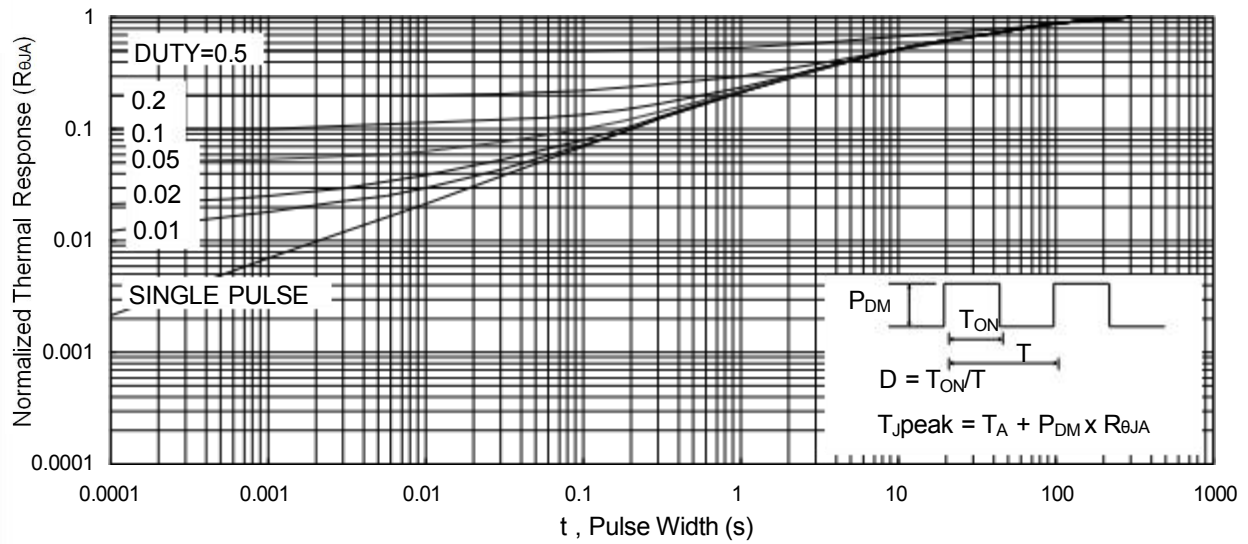


Fig.9 Normalized Maximum Transient Thermal Impedance

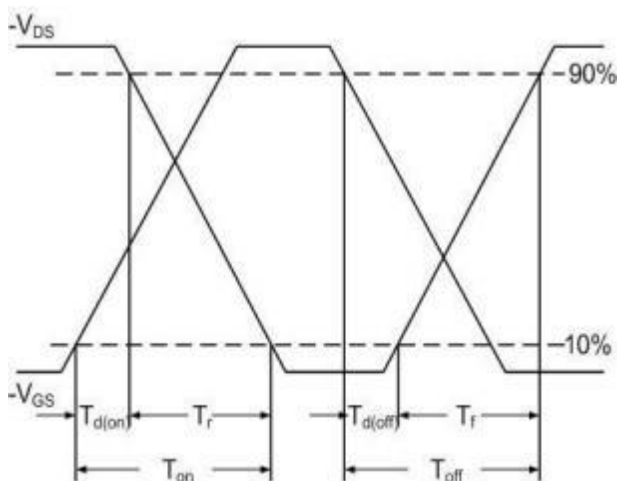


Fig.10 Switching Time Waveform

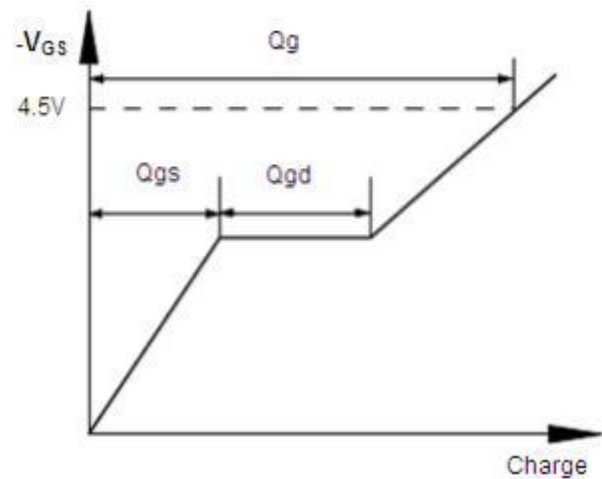
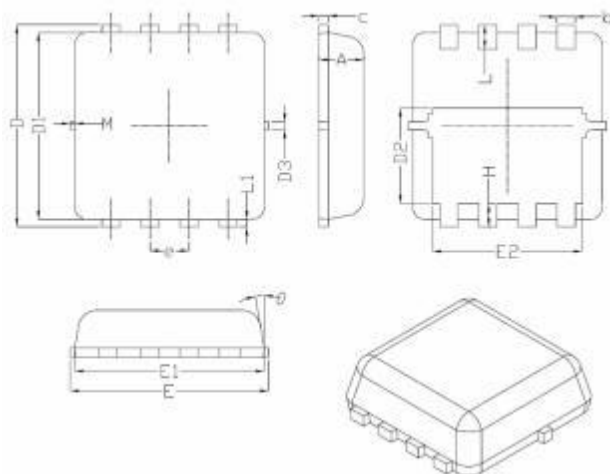


Fig.11 Gate Charge Waveform

DFN3X3-8L Package Information



Symbol	Dimensions In Millimeters		
	Min.	Nom.	Max.
A	0.70	0.75	0.80
b	0.25	0.30	0.35
c	0.10	0.15	0.25
D	3.25	3.35	3.45
D1	3.00	3.10	3.20
D2	1.48	1.58	1.68
D3	-	0.13	-
E	3.20	3.30	3.40
E1	3.00	3.15	3.20
E2	2.39	2.49	2.59
e	0.65BSC		
H	0.30	0.39	0.50
L	0.30	0.40	0.50
L1	-	0.13	-
M	*	*	0.15
θ		10°	12°

REEL SPECIFICATION

P/N	PKG	QTY
MSK30P02DF	DFN3X3-8L	5000

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